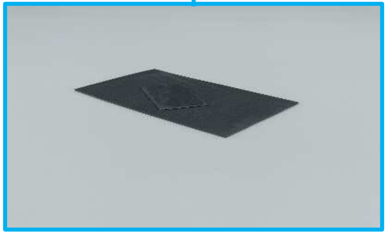
FT_TEL_200_ZS_30

Thermal Pad



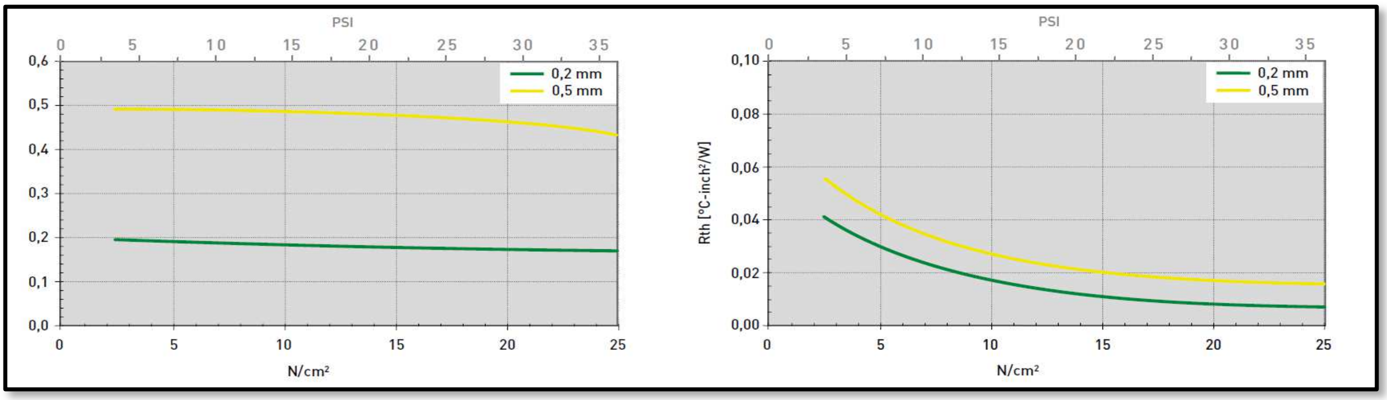
Our Thermal Foams also called Gap Pad or Gap Filler are silicone-based thermo-conductive materials that solve the problems of heat dissipation. The TEL_200_ZS is a mattress specially developed for applications where a low cooling requirement is required. Indeed, it is an excellent thermal conductor of 20W/ mK, with a good thermal resistance facilitating the transfer of heat and does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR ll Module, etc.

Technical characteristics

Features	Unit	TEL_200_ZS		
Thickness	mm	0.2	0.5	-
Reinforcement	-	-		
Color	-	Black		
Hardness	Shore 00	60		
Size	mm	120*120		
Resistance @90 Psi	°C-inch²/W (mm)	0.007 (0.17)	0.018 (0.44)	-
Resistance @30 Psi		0.017 (0.18)	0.027 (0.44)	-
Resistance @10 Psi		0.030 (0.19)	0.042 (0.49)	-
Thermal conductivity	W/mK	20		
Temperature	°C	-40 to 150		
Breakdown voltage	kV/mm	-		
Volume resistance	0hm - cm	< 50,000		
Contante dielectric	@1MHz	-		

The TEL_200_ZS is available in 0.2/0.3/0.5mm thicknesses.



Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user’s responsibility to perform their own tests to ensure that the product meets their needs.